MPPT Solar Converter

SOLAR CAR 2021

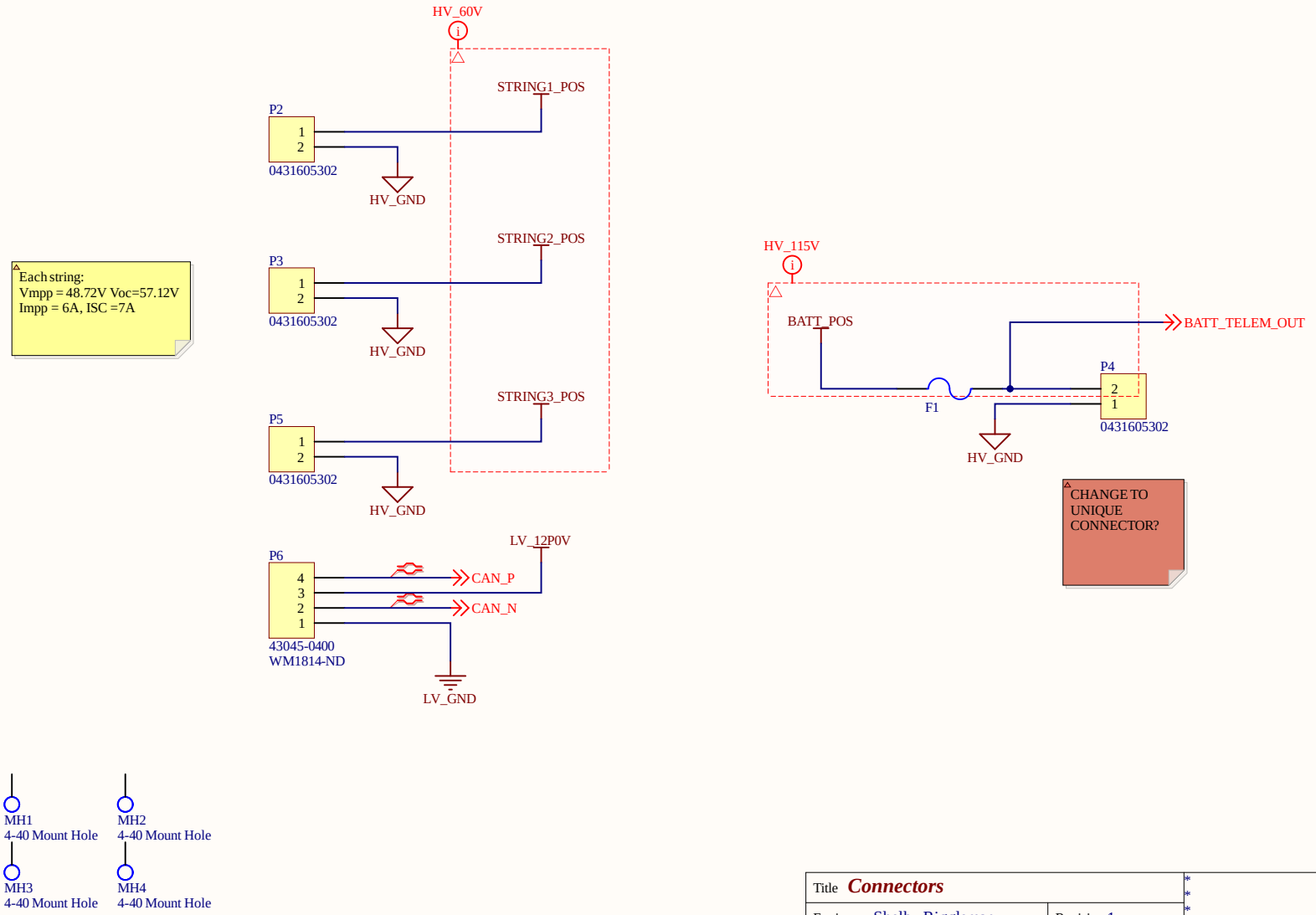
REV 2

Title	***COVER***	
Engineer: Shelby Riggleman		Revision: 1
Date: 4/16/2022	Time: 5:10:38 PM	Sheet 1 of 10
File: cover.SchDoc		

Badgerloop Electrical
133 Engineering Research Building
1500 Engineering Drive
Madison, Wi 53706

BADGER LOOP

Connectors

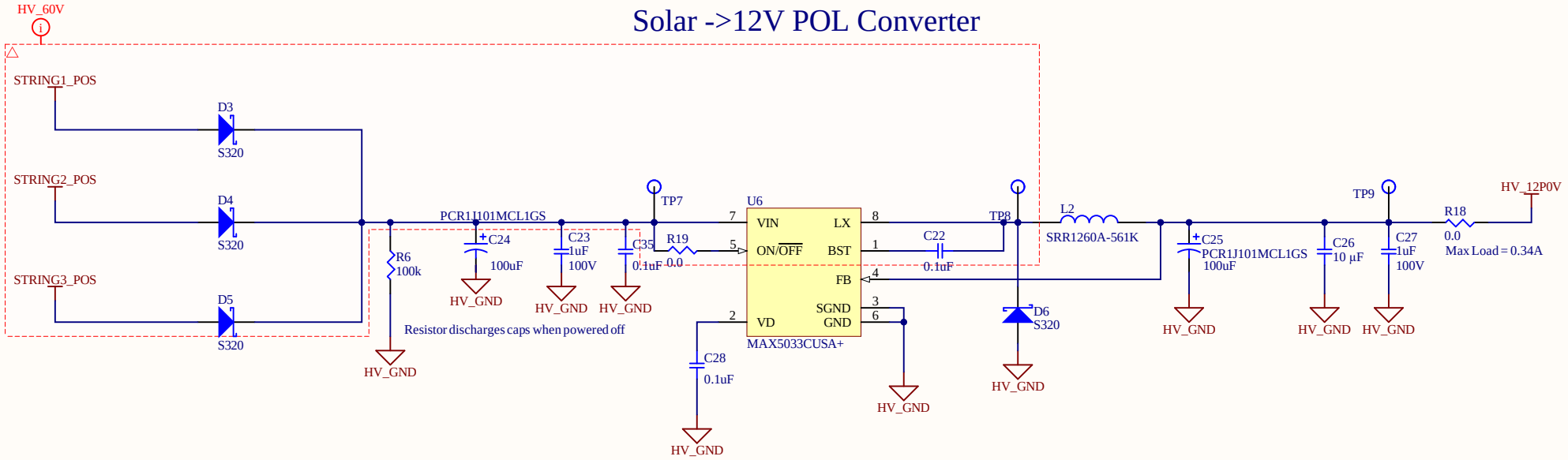


Title	***Connectors***	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:38 PM	Sheet 2 of 10
File: Connectors.SchDoc		

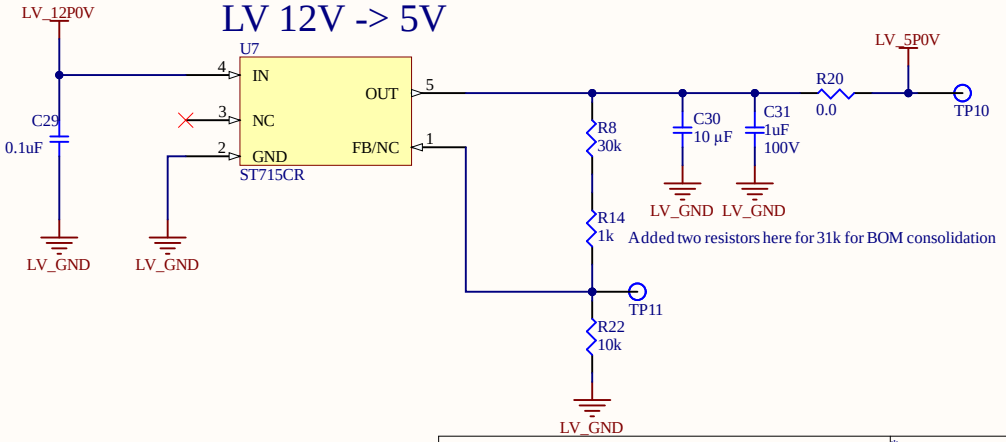
BADGER LOOP

Point of Load Converters

Solar ->12V POL Converter



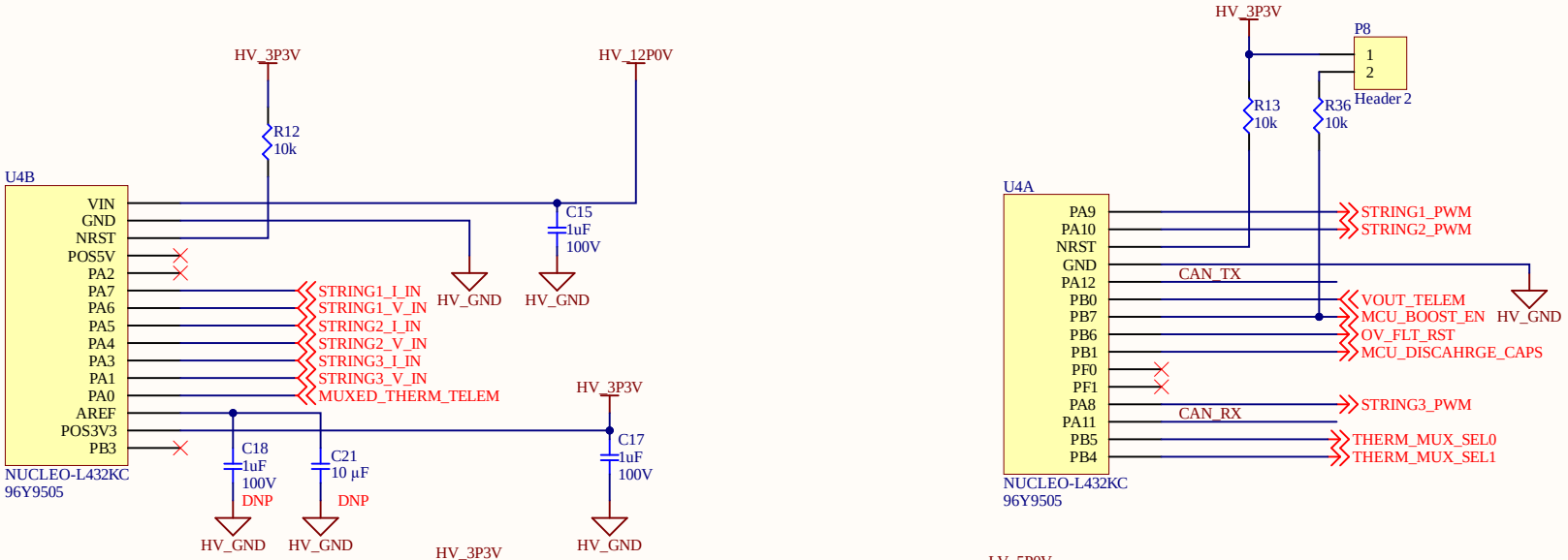
LV 12V -> 5V



Title	***Point of load converters***	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:38 PM	Sheet3 of 10
File: POL_converter.SchDoc		

BADGER LOOP

Nucleo MCU & CAN

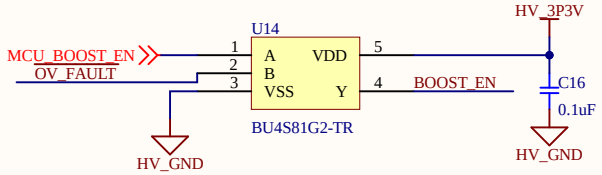


Title	*Nucleo*	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:39 PM	Sheet 4 of 10
File: Nucleo.SchDoc		

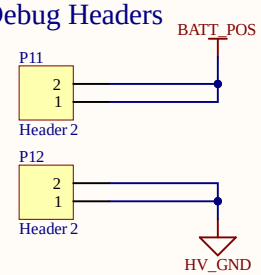
BADGER LOOP

Solar Strings MPPTs

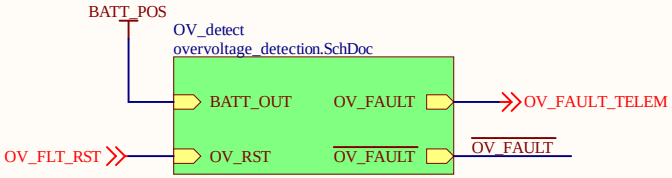
Boost Enable Signal (All)



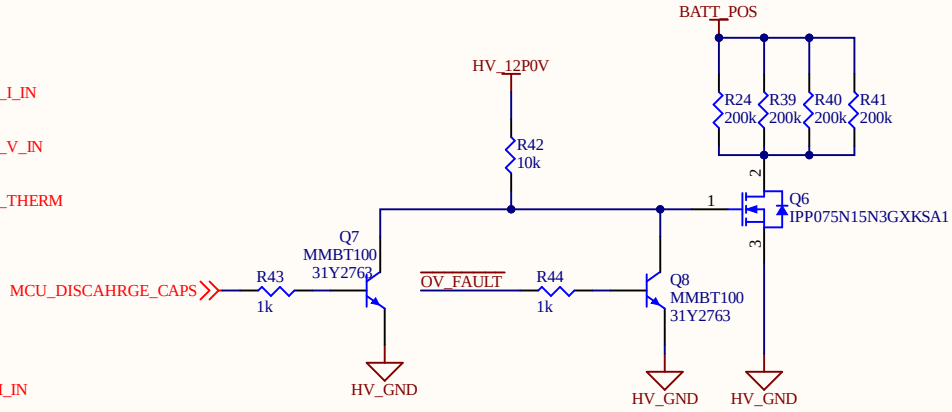
Debug Headers



Overvoltage Detection



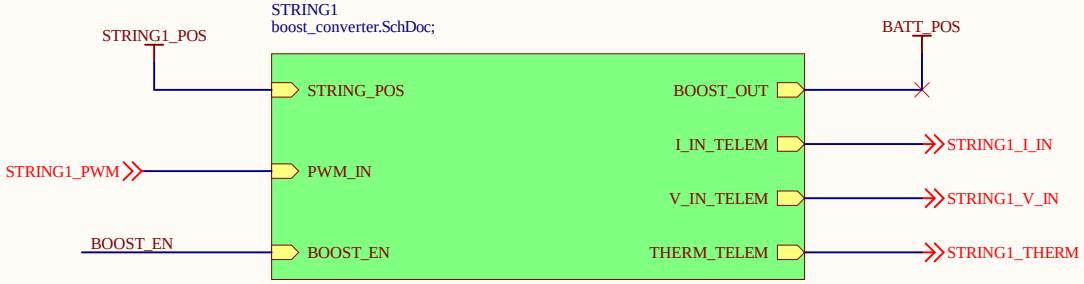
Overvoltage Discharge



Either MCU or OV circuit can discharge caps. Could write code to always use MCU if reading OV feedback

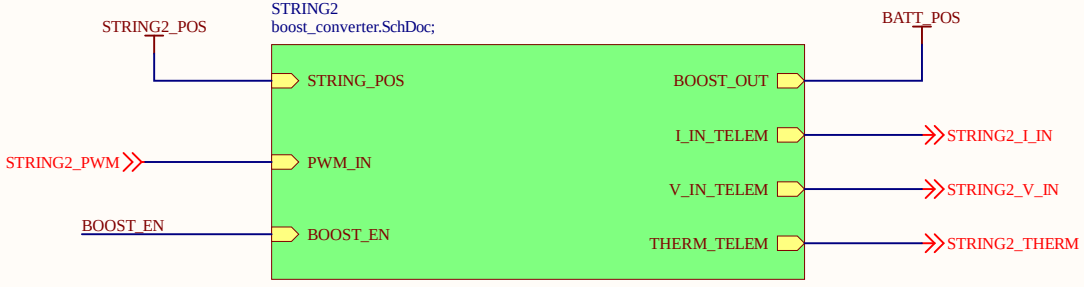
STRING1

boost_converter.SchDoc;



STRING2

boost_converter.SchDoc;



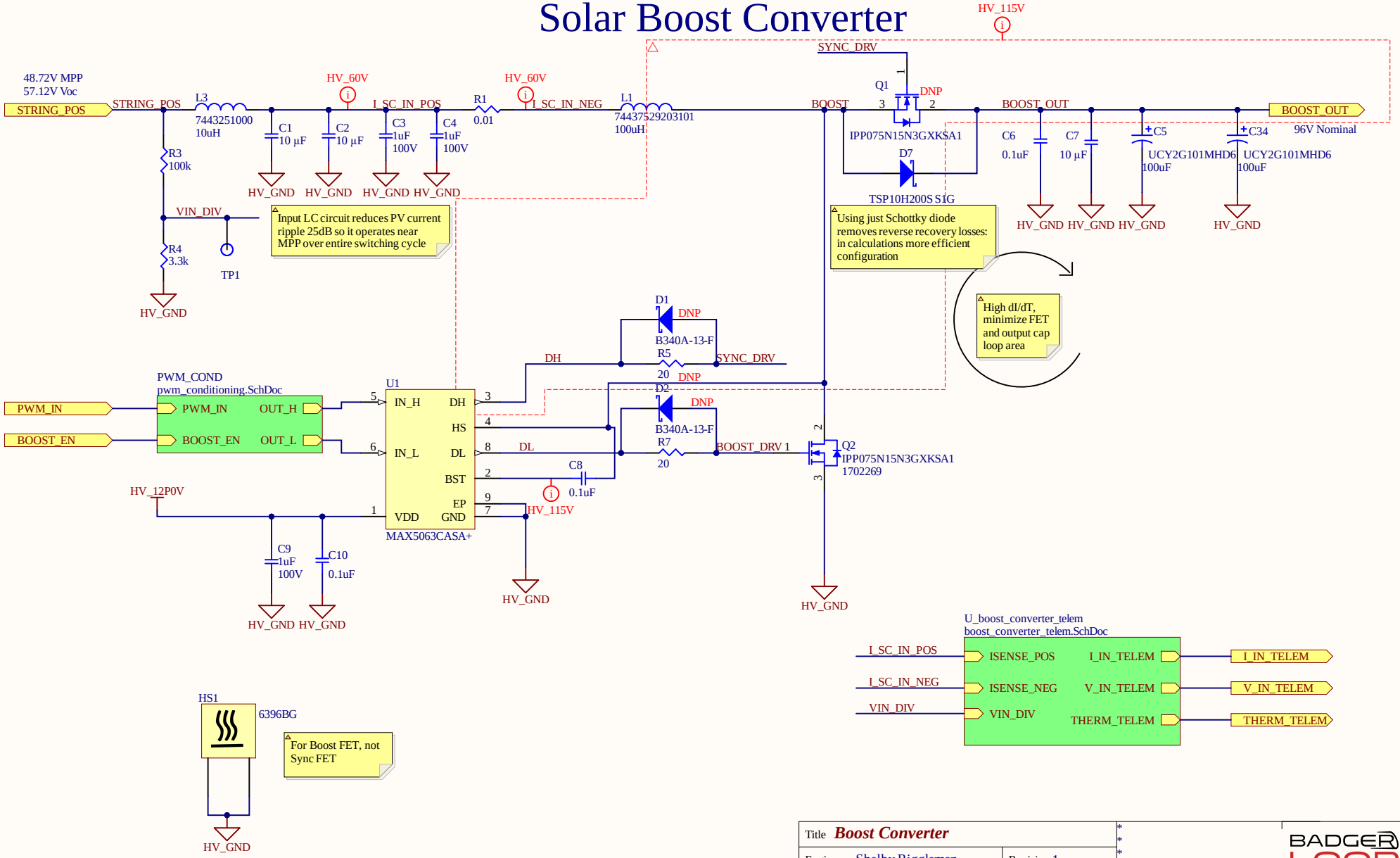
STRING3

boost_converter.SchDoc;

Title	***Boost Strings***
Engineer: Shelby Riggleman	Revision:1
Date: 4/16/2022 Time: 5:10:39 PM	Sheet 5 of 10
File: solar_boost_strings.SchDoc	

BADGER LOOP

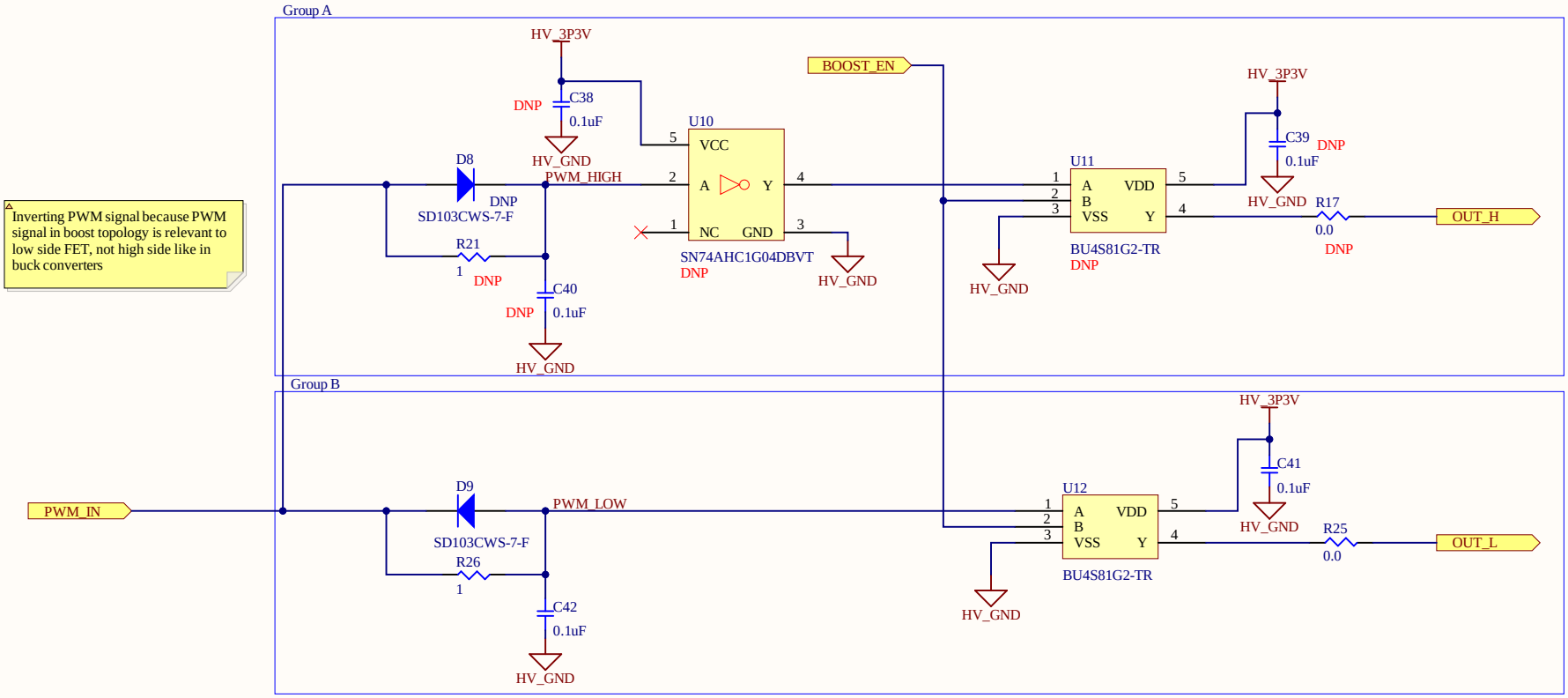
Solar Boost Converter



Title	*Boost Converter*
Engineer:	Shelby Riggleman
Revision:	1
Date:	4/16/2022
Time:	5:10:39 PM
Sheet	6 of 10
File:	boost_converter.SchDoc

BADGER LOOP

PWM Conditioning

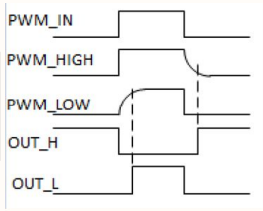


Different populations may be needed dependent on gate driver used/populated as they are available (default is MAX5063C):

Gate Driver	Sync. Config (2 FETS):	Async. Config (FET + Diode)
MAX5063A/MAX5063C	Populate all components	DNP Group A, or remove OUT_H resistor Short out PWM_LOW RC resistor
MIC4102	DNP Group B, or remove OUT_L resistor Short out PWM_HIGH RC resistor	DNP Group B, or remove OUT_L resistor Short out PWM_HIGH RC resistor
MIC4103	Populate all components	DNP Group A, or remove OUT_H resistor Short out PWM_LOW RC resistor

Default Configuration

RC Circuts create delays between FET on times to prevent shoot through when converter is in synchronous configuration:

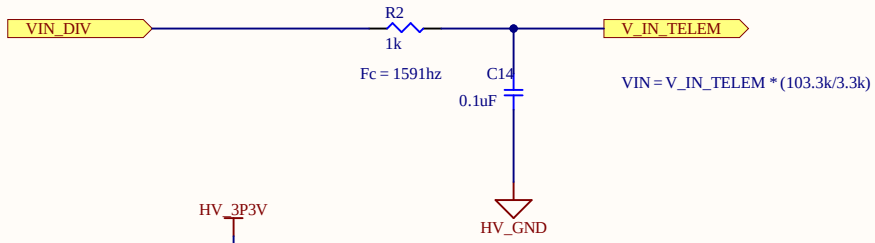


Title	***PWM Conditioning***	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:39 PM	Sheet 7 of 10
File: pwm_conditioning.SchDoc		

BADGER LOOP

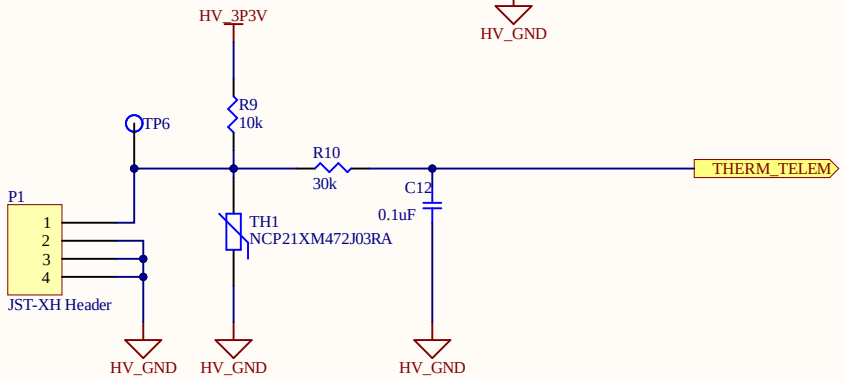
Solar Boost Converter Telemetry

String Input Voltage

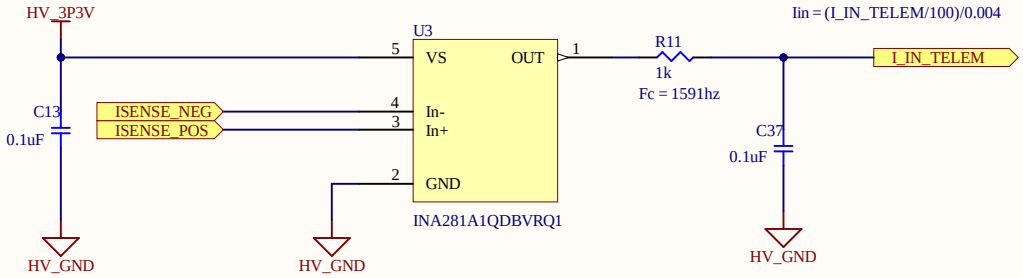


UPDATE COMPONENTS TO CREATE CORNER FREQUENCY HIGHER THAN CONTROL LOOP UPDATE RATE UPON TESTING

Thermistor Output



String Input Current



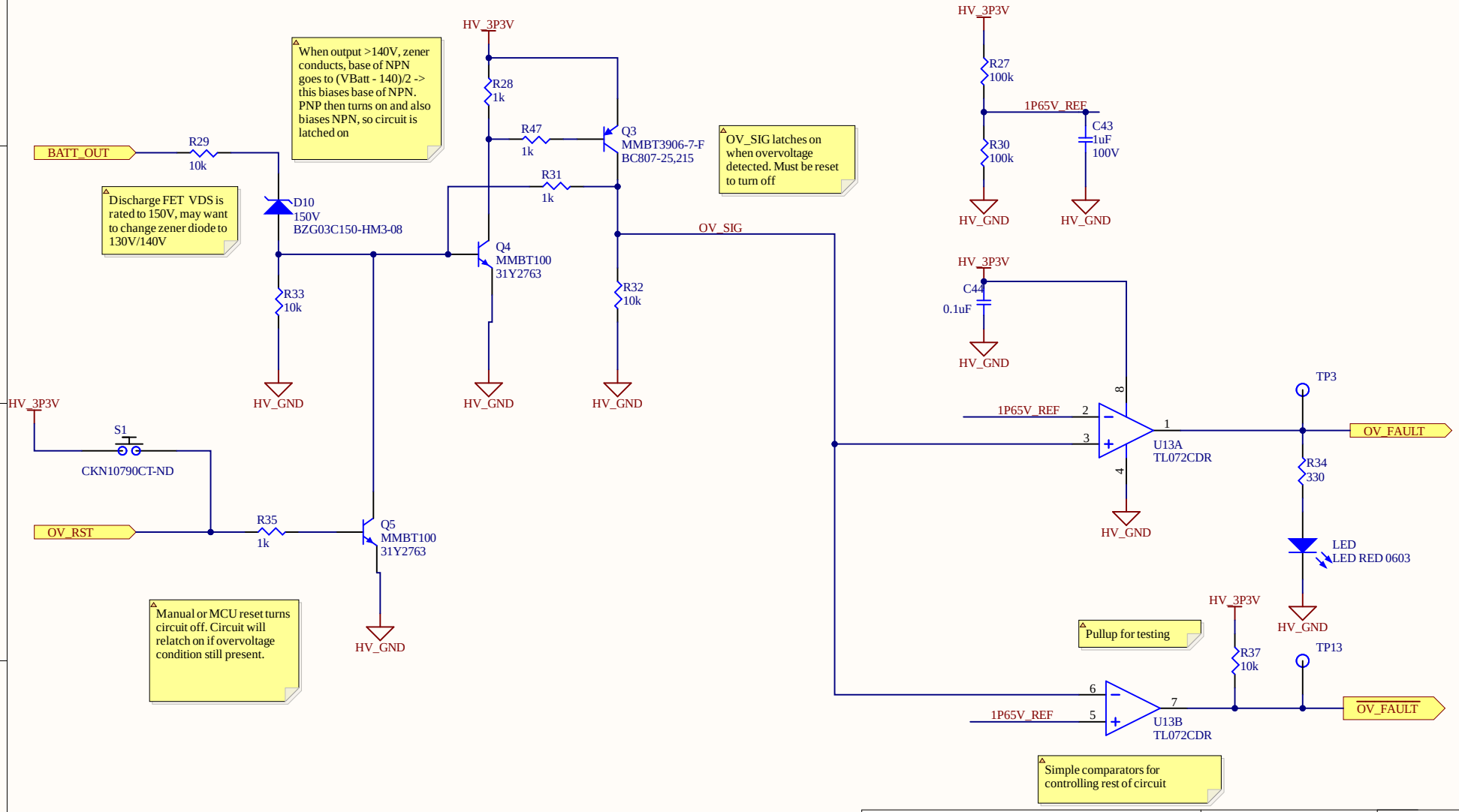
UPDATE COMPONENTS TO CREATE CORNER FREQUENCY HIGHER THAN CONTROL LOOP UPDATE RATE UPON TESTING

INA240 Max input voltage is 80V, cannot use on boost output. Use Vin, Vout, Iin to solve for Iout.

Title	***Boost Converter Telemetry***	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:40 PM	Sheet 8 of 10
File: boost_converter_telem.SchDoc		

BADGER LOOP

Overvoltage Detection

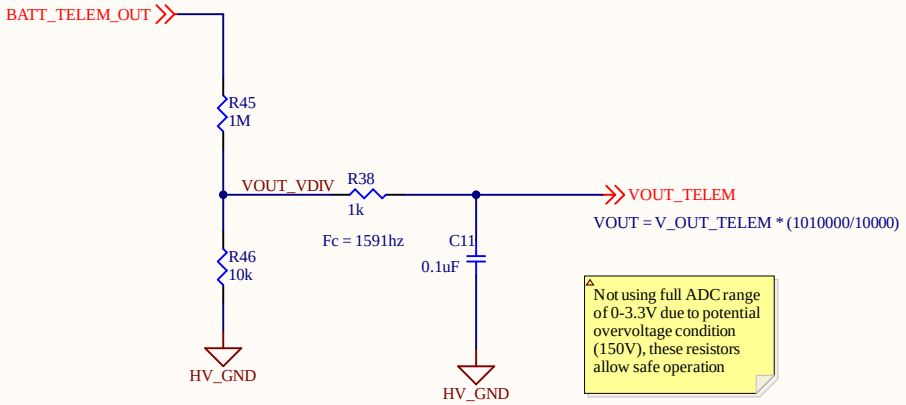


Title	***Over-Voltage Detection***	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:40 PM	Sheet9 of 10
File: overvoltage_detection.SchDoc		

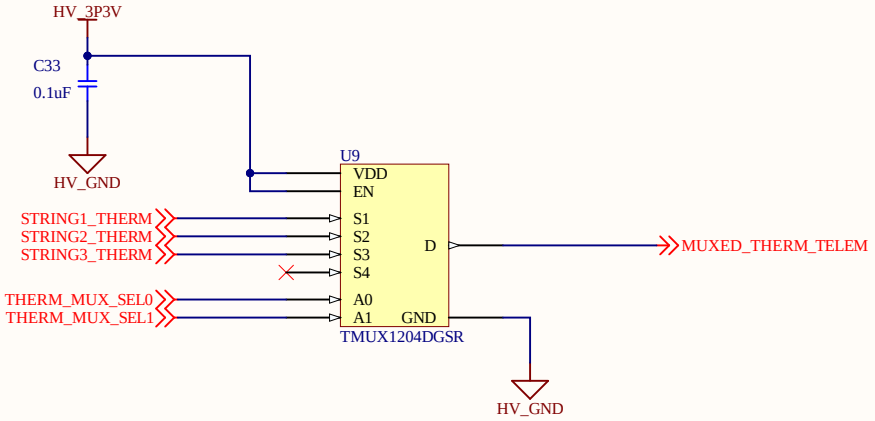
BADGER LOOP

Global Telemetry

Output (Battery) Voltage



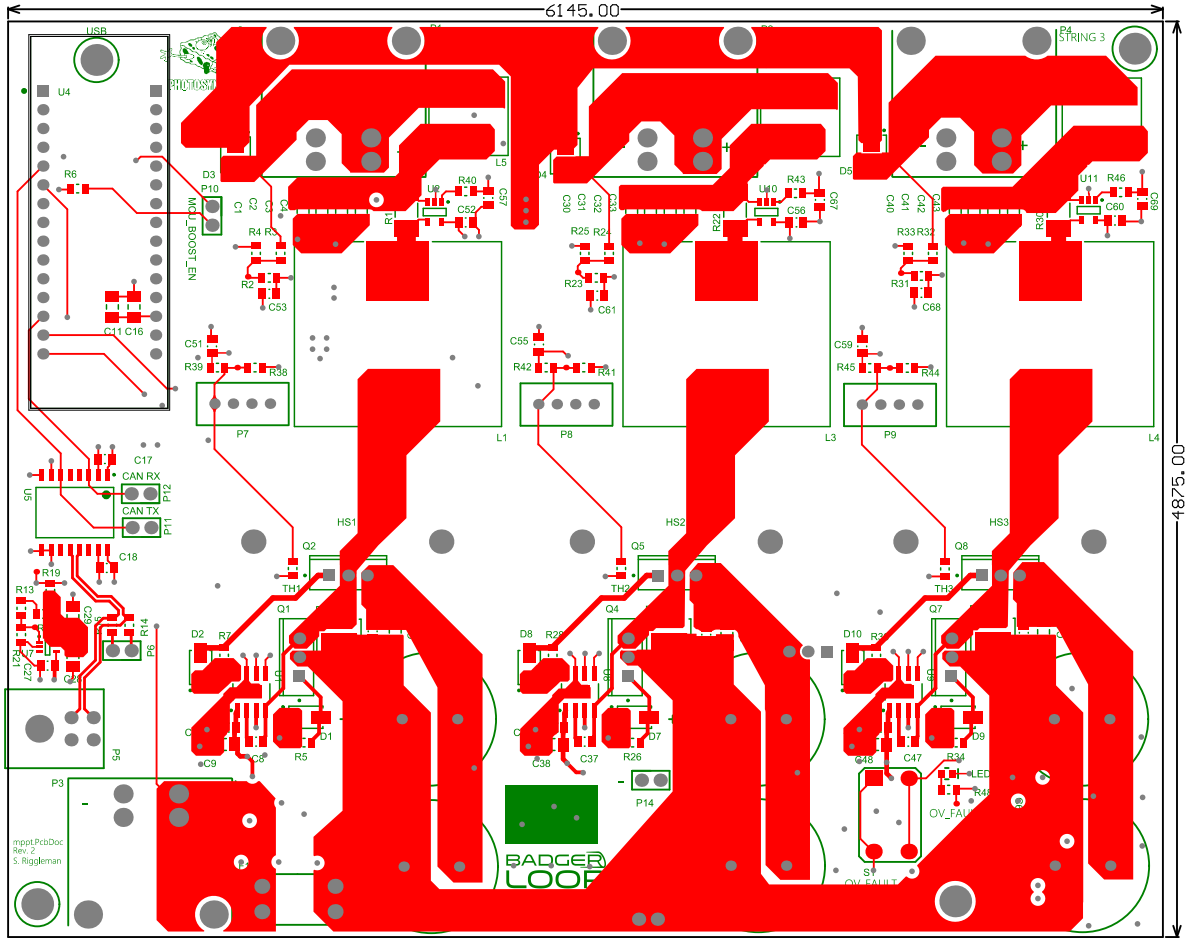
String Thermistor Telem (Muxed)



Title	*Global Telemetry*	
Engineer: Shelby Riggleman		Revision:1
Date: 4/16/2022	Time: 5:10:40 PM	Sheet 10 of 10
File: global_telem.SchDoc		

BADGER LOOP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 2	PP-006	2.80mil	4.1	
2	Layer 1	CF-004	1.38mil		
	Dielectric 1	FR-4	12.60mil	4.8	
3	Layer 2	CF-004	1.38mil		
	Dielectric 3	PP-006	2.80mil	4.1	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



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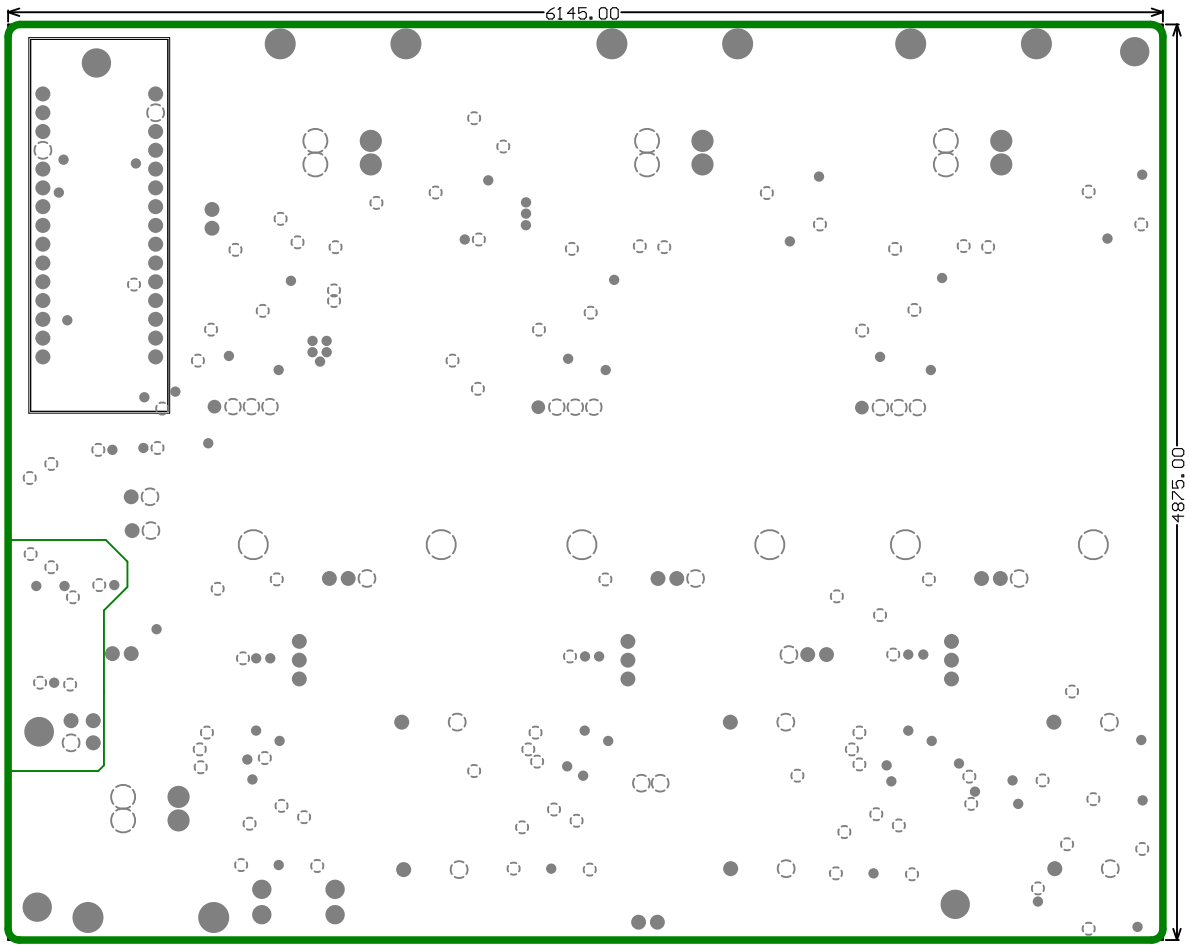
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



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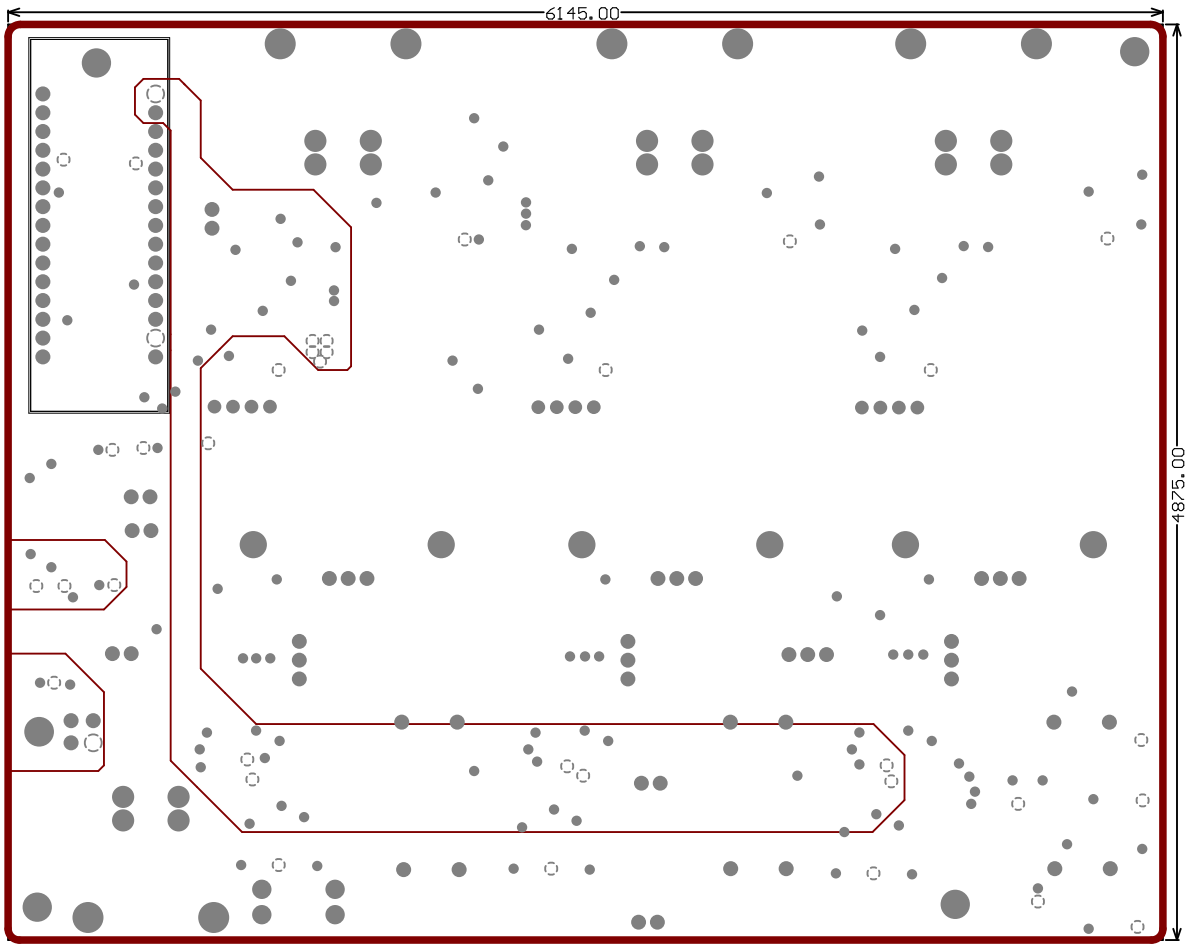
	Bottom Overlay				



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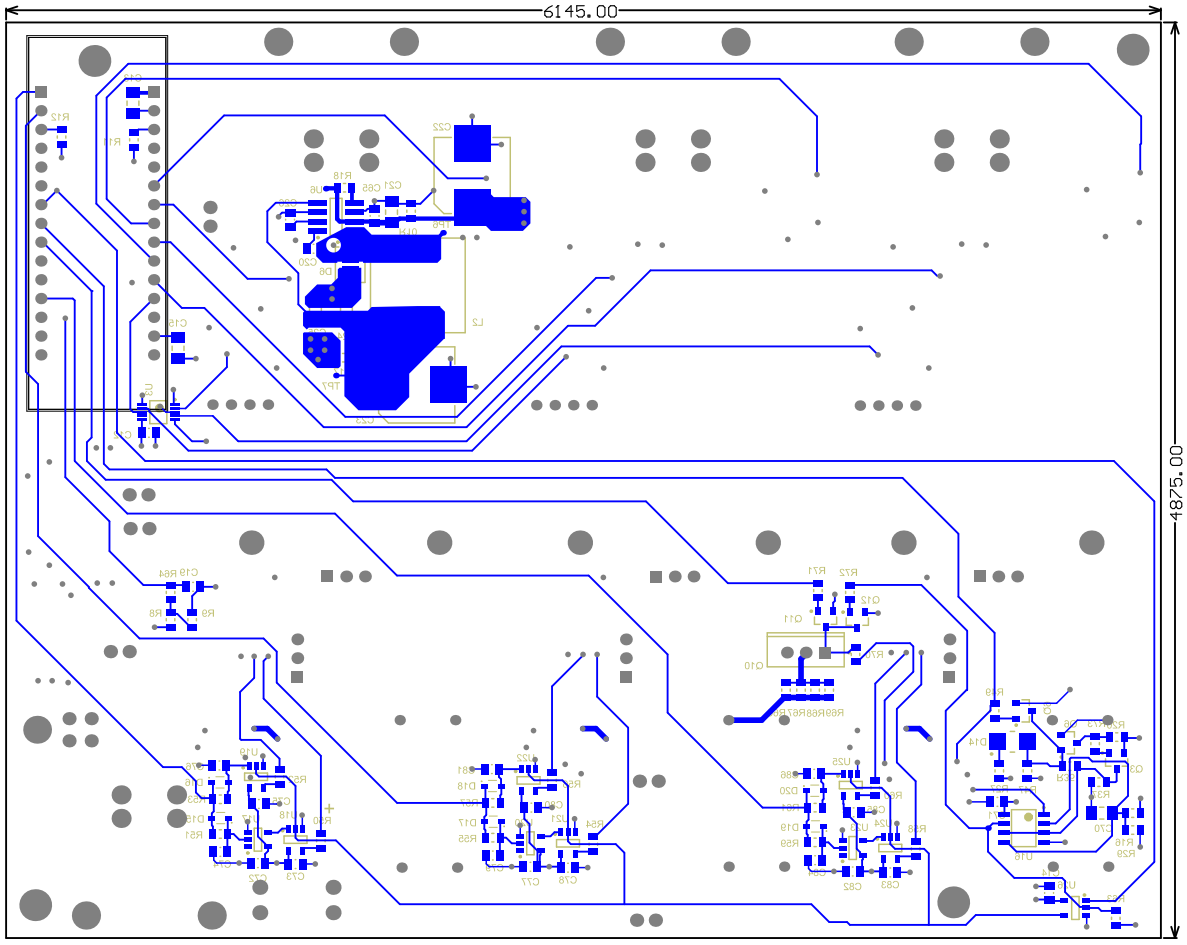

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